INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Op POU92	otional) 0000148US	Application Number		
Applicant(s) Chu et al	Express Ma	il Label #ET089965406US	5	
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				U.S. PAT	ENT DOCUMENTS				
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE		NAME	CLASS	SUBCLASS FILING DAT		
P	Α	5388635	2/14/95	Gruber et al		165	80.4	0 10	
P	В	5592363	1/7/97	Atarasl	Atarashi et al		689	S	~ === m
10	С	5647430	7/15/97	Tajima	Tajima		104.33	27 7	
P	D	5871043	2/16/99	Osakab	Osakabe et al		104.21	109	
N	E	5925929	10/28/96	Kuwah	Kuwahara et al		714		
N	F	5949646	9/7/99	Lee et a	Lee et al		695		
N	G	5986882	11/16/99	Ekrot et al		361	687		
N	н	5998863	12/7/99	Kobayashi et al		257	715		
N	I	6223810	5/1/01	Chu et al		165	104.33		-
N	J	5953930	9/21/99	Chu e	et al	62	259.2		
W	К	Serial No. 09/736,455	Pending	Chu et al				12/14/2000	
				FOREIG	N PATENT DOCUMEN	NTS			
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				OTHER	DOCUMENTS (Incl	luding Author, Title, D	ate. Pertinent Pa	es. Etc.)	
i				V	DOCUMENTS (Inc.			,, ,	

		OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)
W		IBM Technical Disclosure Bulletin, Vol. 20, No. 2, July 1977, pp. 673-674, "Liquid Cooled Module With Compliant Membrane" by Loeffel et al
M	M	"Fundamentals Of Heat and Mass Transfer" by Incropera et al, 1990, Third Edition, Chapter 3 - One-Dimensional, Steady-State Conduction, pp. 130-135 and Fourth Edition - Chapter 3, pp. 122-123
N	·N	Momentum, Heat, and Mass Transfer by C. O. Bennet, 1962, pp. 406-407

EXAMINER Wilm. Fax

DATE CONSIDERED 09.08.03

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.